



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

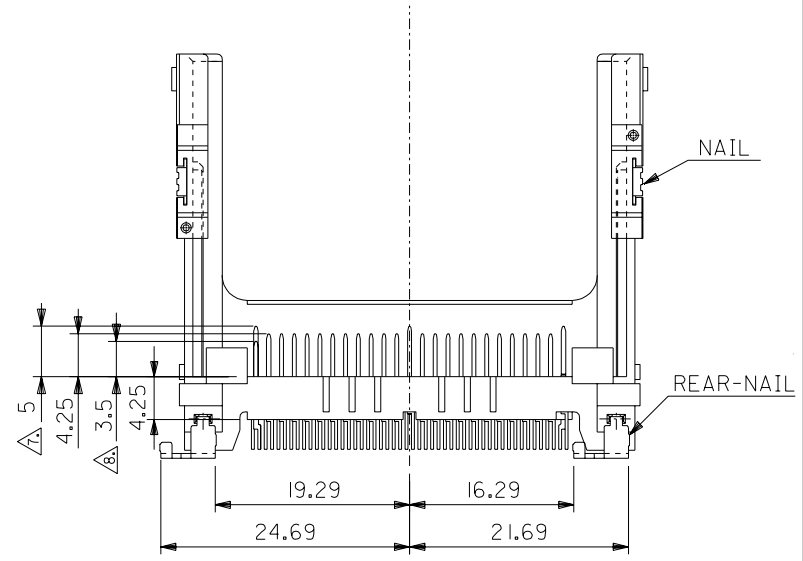
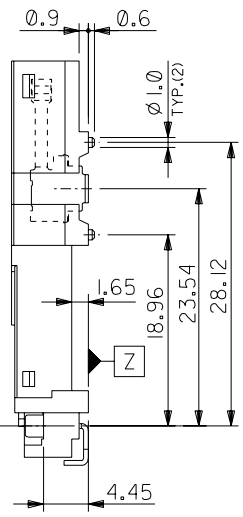
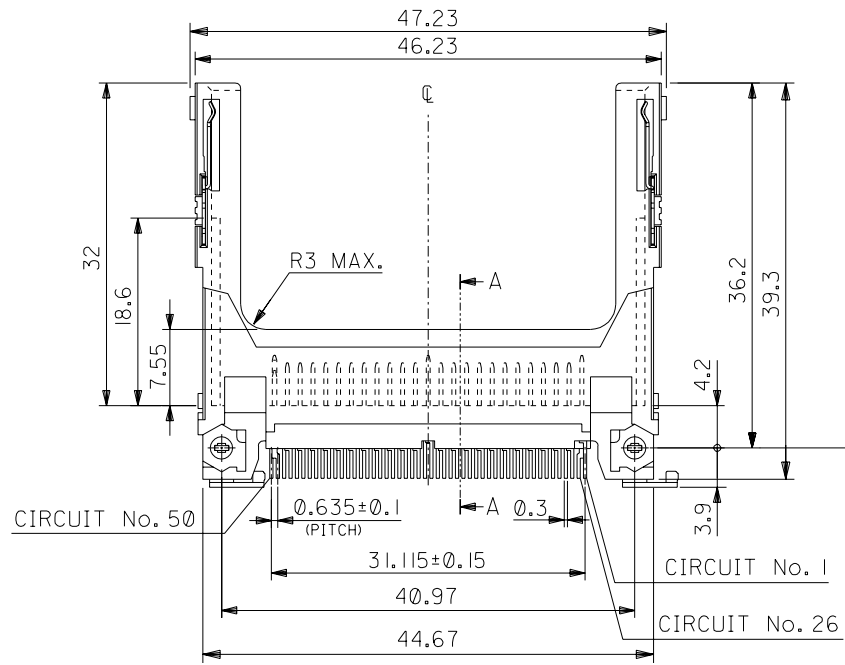
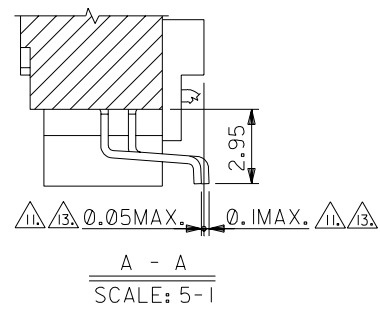
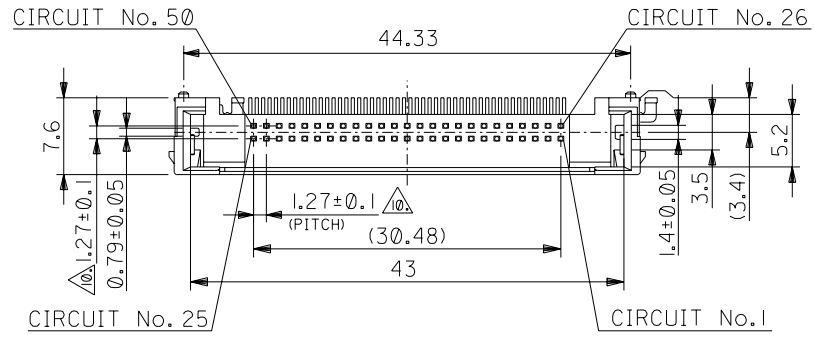
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DWG. NO. SD-55358-014



DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:
RELEASED				
EC NO. J2004-3952				
DRWN: M.NABEI '04/04/22				
CHK: K.TOJO '04/04/22				
APPR: M.SASAO '04/04/22				

MATERIAL 材料	SEE NOTES
FINISH 仕上り	SEE NOTES
WIRE RANGE 適用線径範囲	#
INS. RANGE 被覆外径	#

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 30 UNDER 以上 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

55358-5028		55358-5029		55358-50**	
HARD TRAY PACKAGE		MATERIAL No.		MODEL No.	
SCALE 2 - 1	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input type="checkbox"/> mm <input checked="" type="checkbox"/> INCH ONLY		SHT	REV
DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-			
CHECKED BY & DATE K.TOJO '04/04/22		MATERIAL NO. SEE CHART			
APPROVED BY & DATE M. Sasao '04/04/22		DRAWING NO. SD-55358-014		SHEET NO. 1 OF 2	
CAD FILENAME SD-55358-014.S01		DRAWING NO. SD-55358-014		SHEET NO. 1 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					SIZE B

SD-55358-014.S01

DWG. NO. SD-55358-014

F

D

V

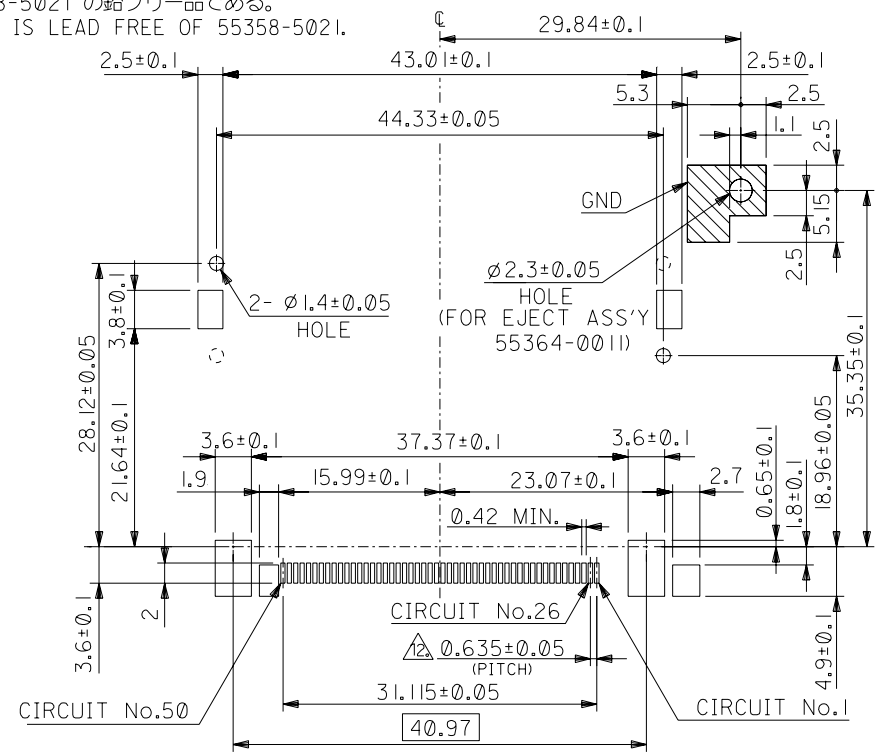
C

B

DO NOT SCALE DRAWING

- 注) 1. 材質 MATERIAL  
 ハウジング: ガラス入りLCP UL94V-0  
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0  
 ピン: リン青銅  
 PIN: PHOSPHOR BRONZE  
 ネール: リン青銅 (t0.3)  
 NAIL: PHOSPHOR BRONZE (t0.3)  
 リヤネール: リン青銅 (t0.48)  
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING  
 ピン PIN 接点部: パラジウムニッケル下地、金メッキ  
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 ネール NAIL 接点部: 金メッキ  
 CONTACT AREA: GOLD  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 リヤネール REAR-NAIL 錫メッキ  
 TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚: t=0.8 MIN.  
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)  
 RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1  
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒  
 HOUSING COLOR: BLACK
7. 寸法適用極: 1,13,38,50  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
8. 寸法適用極: 25,26  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

11. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。  
 SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDERTAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDERTAILS TIP.
12. 公差非累積 NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。  
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5021 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 55358-5021.



基板推奨寸法  
 RECOMMENDED P.C.B. LAYOUT

EC NO.		EC NO.		EC NO.		EC NO.		EC NO.		55358-50**		MODEL NO.		DIMENSIONS:		SHT		REV	
DRWN:	CHK:	DRWN:	CHK:	DRWN:	CHK:	DRWN:	CHK:	DRWN:	CHK:	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	mm	INCH	mm	INCH	REVISE ON CAD ONLY		
										2	mm	INCH	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>			
SEE NOTES										DRAWN BY & DATE		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-							
SEE NOTES										M.NABEI '04/04/22		MATERIAL NO. SD-55358-014.S02							
SEE NOTES										CHECKED BY & DATE		DRAWING NO. SD-55358-014							
SEE NOTES										K.TOJO '04/04/22		SHEET NO. 2							
SEE NOTES										APPROVED BY & DATE		MATERIAL NO. SD-55358-014							
SEE NOTES										M. Saito '04/04/22		DRAWING NO. SD-55358-014							
SEE NOTES										CAD FILENAME		SHEET NO. 2							
SEE NOTES										SD-55358-014.S02		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.							
SEE NOTES										ANGLE 角度		SIZE B							
SEE NOTES										3°		EN-02J(097) MXJ-54							

SD-55358-014.S02